

L Number	Hits	Search Text	DB	Time stamp
3	2602	((438/107) or (438/406) or (438/422) or (438/455) or (438/456) or (438/459) or (438/960)).CCLS.	USPAT; US-PGPUB	2004/10/20 13:39
4	1177	((438/107) or (438/406) or (438/422) or (438/455) or (438/456) or (438/459) or (438/960)).CCLS.) and (@ad < "19990719")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 13:40
-	11	(("6,020,252") or ("5,985,681") or ("5,882,987") or ("5,374,564") or ("5,714,395") or ("6,331,208") or ("5,371,037") or ("6,171,982") or ("6,342,433") or ("6,294,478") or ("6,271,101")).PN.	USPAT	2004/06/21 16:01
-	41	((separat\$4 or cleav\$4 ) same porous\$4 ) and (semiconductor or silicium or si) and (smart-cut\$4 or smart adj cut\$4 or ("h.sub.2" or hydrogen) near4 (inplant\$4 or implant\$4)) ) and (@ay < "2000")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 12:22
-	1616	(separat\$4 or cleav\$4 or smart-cut\$4 or smart adj cut\$4) near4 (porous\$4) same (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 12:25
-	523	((separat\$4 or cleav\$4 or smart-cut\$4 or smart adj cut\$4) near4 (porous\$4) same (wafer or substrate)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 12:25
-	306	((separat\$4 or cleav\$4 or smart-cut\$4 or smart adj cut\$4) near4 (porous\$4) same (wafer or substrate)).ab. ) and (@ad < "19990719")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/20 13:39